

SOT1085-1

plastic low profile fine-pitch ball grid array package; 273 balls

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFPGA273
Package type industry code	LFPGA273
Package style descriptive code	LFPGA (low profile fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-195
Mounting method type	S (surface mount)
Issue date	29-4-2008

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	9.9	-	10	10.1	mm
E	package width	9.9	-	10	10.1	mm
A	seated height	1.05	-	1.16	1.3	mm
A ₂	package height	0.85	-	0.91	1	mm
n ₂	actual quantity of termination	-	-	273	-	



2. Package outline

LFBGA273: plastic low profile fine-pitch ball grid array package; 273 balls SOT1085-1

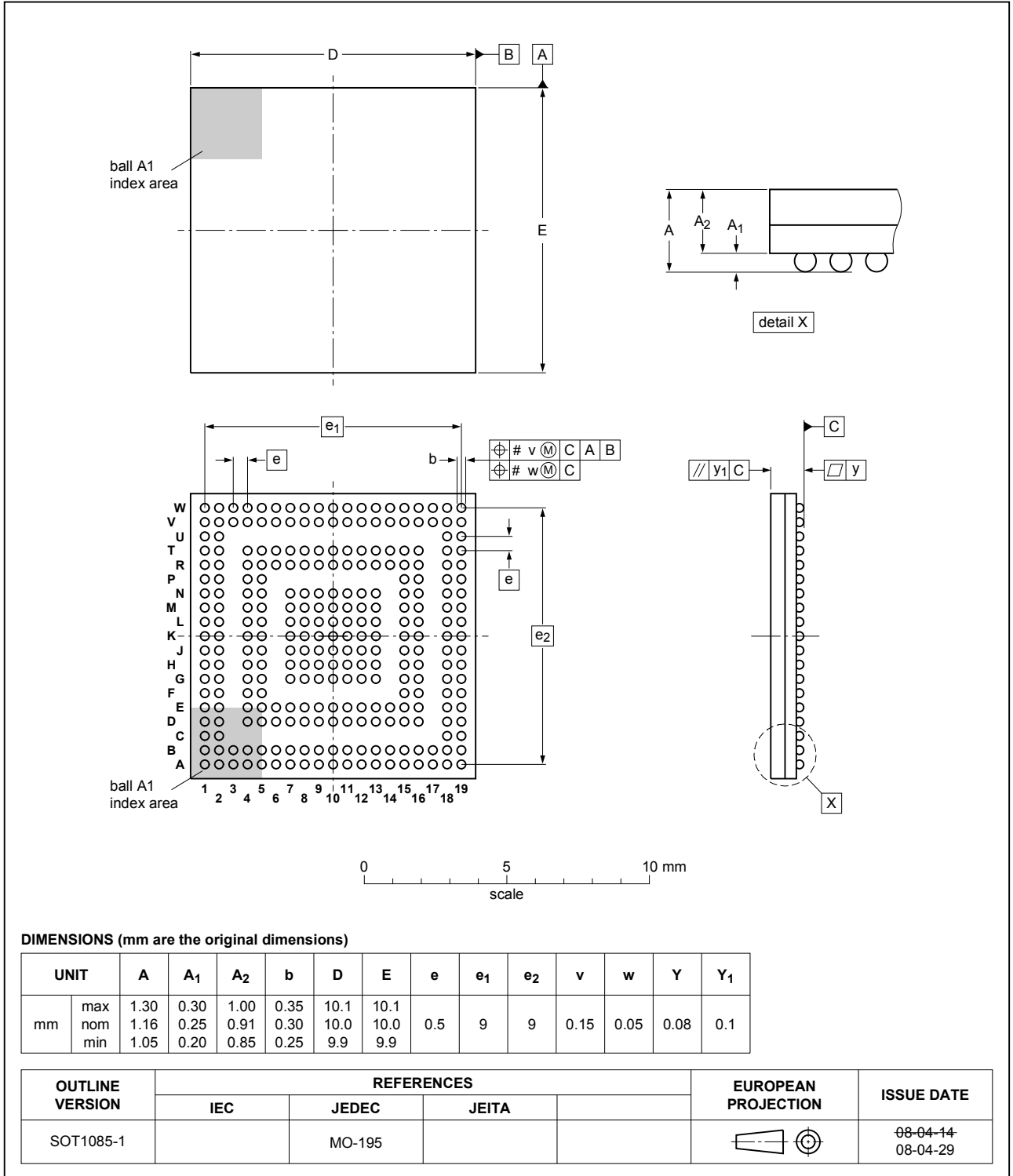


Fig. 1. Package outline LFBGA273 (SOT1085-1)

3. Soldering

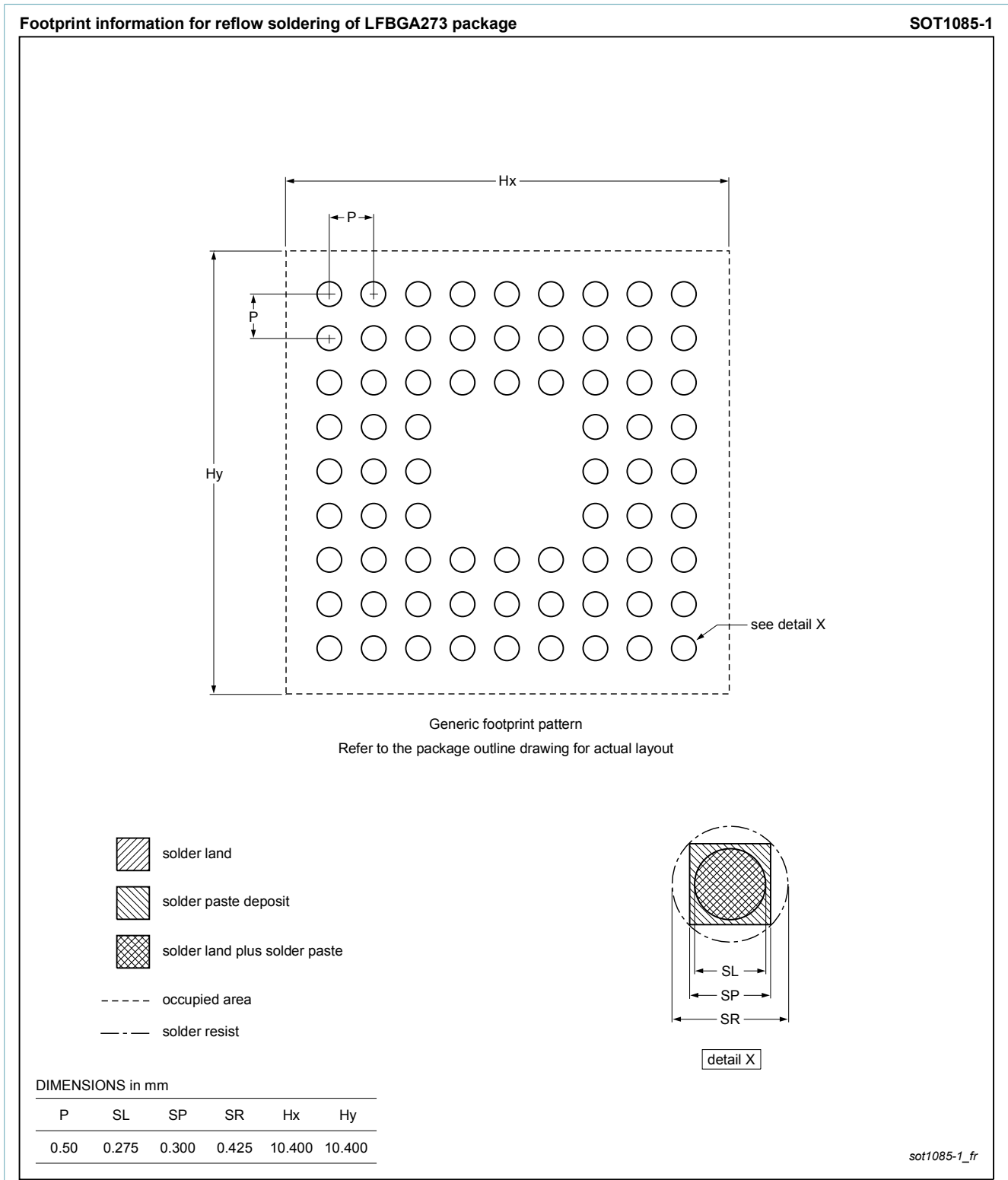


Fig. 2. Reflow soldering footprint for LFBGA273 (SOT1085-1)

4. Legal information

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